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### Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

### Applications of Embedded - FPGAs






The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

#### Details

Product Status	Obsolete
Number of LABs/CLBs	2566
Number of Logic Elements/Cells	25660
Total RAM Bits	1944576
Number of I/O	597
Number of Gates	-
Voltage - Supply	1.425V ~ 1.575V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	780-BBGA
Supplier Device Package	780-FBGA (29x29)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/intel/ep1s25f780i6">https://www.e-xfl.com/product-detail/intel/ep1s25f780i6</a>

# Typographic Conventions

This document uses the typographic conventions shown below.

Visual Cue	Meaning
<b>Bold Type with Initial Capital Letters</b>	Command names, dialog box titles, checkbox options, and dialog box options are shown in bold, initial capital letters. Example: <b>Save As</b> dialog box.
<b>bold type</b>	External timing parameters, directory names, project names, disk drive names, filenames, filename extensions, and software utility names are shown in bold type. Examples: <b>f<sub>MAX</sub></b> , <b>lqdesigns</b> directory, <b>d:</b> drive, <b>chiptrip.gdf</b> file.
<i>Italic Type with Initial Capital Letters</i>	Document titles are shown in italic type with initial capital letters. Example: <i>AN 75: High-Speed Board Designs</i> .
<i>Italic type</i>	Internal timing parameters and variables are shown in italic type. Examples: <i>t<sub>PIA</sub></i> , <i>n + 1</i> .  Variable names are enclosed in angle brackets (< >) and shown in italic type. Example: <file name>, <project name>.pof file.
Initial Capital Letters	Keyboard keys and menu names are shown with initial capital letters. Examples: Delete key, the Options menu.
“Subheading Title”	References to sections within a document and titles of on-line help topics are shown in quotation marks. Example: “Typographic Conventions.”
Courier type	Signal and port names are shown in lowercase Courier type. Examples: data1, tdi, input. Active-low signals are denoted by suffix n, e.g., resetn.  Anything that must be typed exactly as it appears is shown in Courier type. For example: c:\qdesigns\tutorial\chiptrip.gdf. Also, sections of an actual file, such as a Report File, references to parts of files (e.g., the AHDL keyword SUBDESIGN), as well as logic function names (e.g., TRI) are shown in Courier.
1., 2., 3., and a., b., c., etc.	Numbered steps are used in a list of items when the sequence of the items is important, such as the steps listed in a procedure.
	Bullets are used in a list of items when the sequence of the items is not important.
	The checkmark indicates a procedure that consists of one step only.
	The hand points to information that requires special attention.
	The angled arrow indicates you should press the Enter key.
	The feet direct you to more information on a particular topic.

The memory address depths and output widths can be configured as  $4,096 \times 1$ ,  $2,048 \times 2$ ,  $1,024 \times 4$ ,  $512 \times 8$  (or  $512 \times 9$  bits),  $256 \times 16$  (or  $256 \times 18$  bits), and  $128 \times 32$  (or  $128 \times 36$  bits). The  $128 \times 32$ - or  $36$ -bit configuration is not available in the true dual-port mode. Mixed-width configurations are also possible, allowing different read and write widths. Tables 2–5 and 2–6 summarize the possible M4K RAM block configurations.

**Table 2–5. M4K RAM Block Configurations (Simple Dual-Port)**

Read Port	Write Port								
	$4K \times 1$	$2K \times 2$	$1K \times 4$	$512 \times 8$	$256 \times 16$	$128 \times 32$	$512 \times 9$	$256 \times 18$	$128 \times 36$
$4K \times 1$	✓	✓	✓	✓	✓	✓			
$2K \times 2$	✓	✓	✓	✓	✓	✓			
$1K \times 4$	✓	✓	✓	✓	✓	✓			
$512 \times 8$	✓	✓	✓	✓	✓	✓			
$256 \times 16$	✓	✓	✓	✓	✓	✓			
$128 \times 32$	✓	✓	✓	✓	✓	✓			
$512 \times 9$							✓	✓	✓
$256 \times 18$							✓	✓	✓
$128 \times 36$							✓	✓	✓

**Table 2–6. M4K RAM Block Configurations (True Dual-Port)**

Port A	Port B						
	$4K \times 1$	$2K \times 2$	$1K \times 4$	$512 \times 8$	$256 \times 16$	$512 \times 9$	$256 \times 18$
$4K \times 1$	✓	✓	✓	✓	✓		
$2K \times 2$	✓	✓	✓	✓	✓		
$1K \times 4$	✓	✓	✓	✓	✓		
$512 \times 8$	✓	✓	✓	✓	✓		
$256 \times 16$	✓	✓	✓	✓	✓		
$512 \times 9$						✓	✓
$256 \times 18$						✓	✓

When the M4K RAM block is configured as a shift register block, you can create a shift register up to 4,608 bits ( $w \times m \times n$ ).

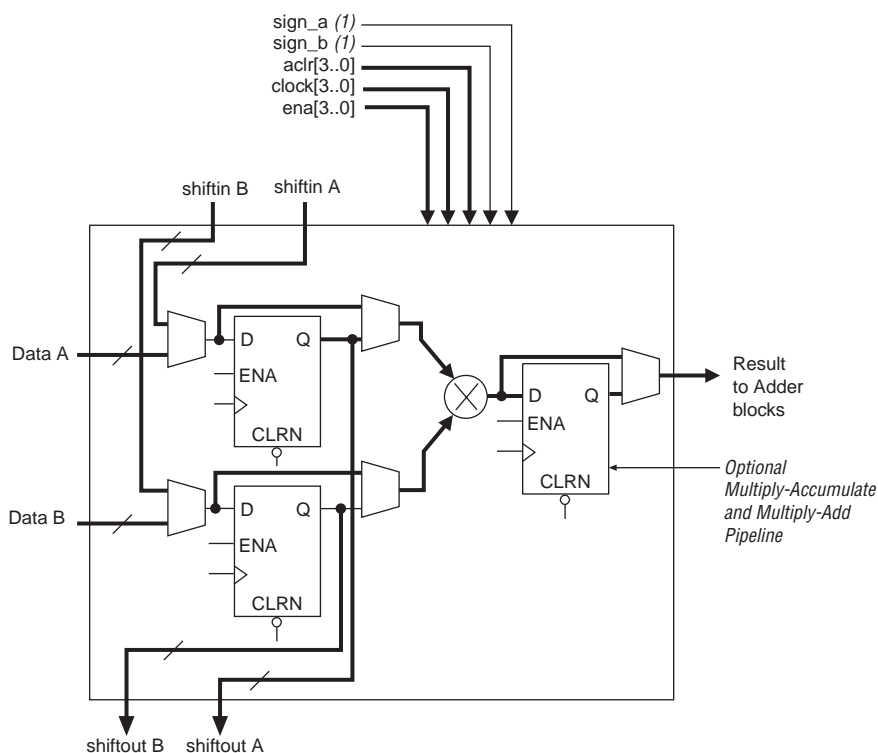
The DSP block consists of the following elements:

- Multiplier block
- Adder/output block

## Multiplier Block

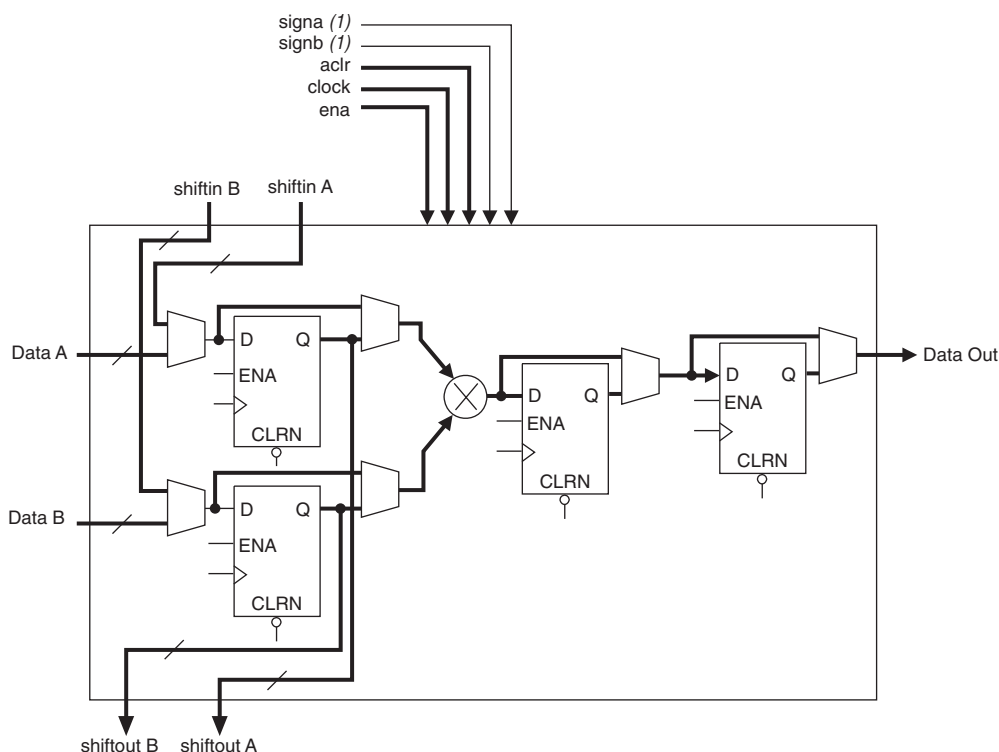
The DSP block multiplier block consists of the input registers, a multiplier, and pipeline register for pipelining multiply-accumulate and multiply-add/subtract functions as shown in Figure 2–32.

**Figure 2–32. Multiplier Sub-Block within Stratix DSP Block**



**Note to Figure 2–32:**

- (1) These signals can be unregistered or registered once to match data path pipelines if required.

**Figure 2–35. Simple Multiplier Mode****Note to Figure 2–35:**

- (1) These signals are not registered or registered once to match the data path pipeline.

DSP blocks can also implement one  $36 \times 36$ -bit multiplier in multiplier mode. DSP blocks use four  $18 \times 18$ -bit multipliers combined with dedicated adder and internal shift circuitry to achieve 36-bit multiplication. The input shift register feature is not available for the  $36 \times 36$ -bit multiplier. In  $36 \times 36$ -bit mode, the device can use the register that is normally a multiplier-result-output register as a pipeline stage for the  $36 \times 36$ -bit multiplier. Figure 2–36 shows the  $36 \times 36$ -bit multiply mode.

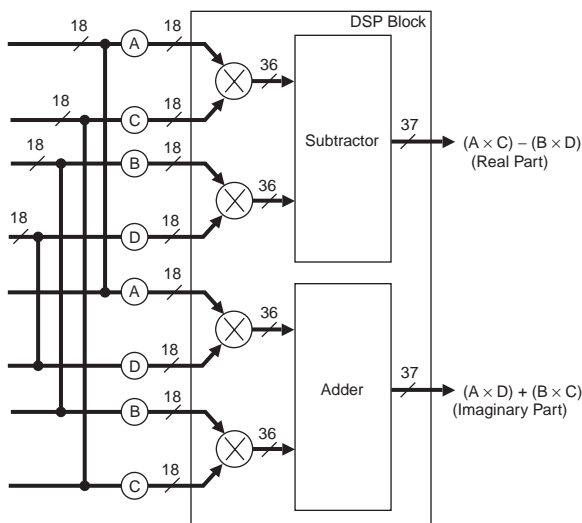
single DSP block can implement two sums or differences from two  $18 \times 18$ -bit multipliers each or four sums or differences from two  $9 \times 9$ -bit multipliers each.

You can use the two-multipliers adder mode for complex multiplications, which are written as:

$$(a + jb) \times (c + jd) = [(a \times c) - (b \times d)] + j \times [(a \times d) + (b \times c)]$$

The two-multipliers adder mode allows a single DSP block to calculate the real part  $[(a \times c) - (b \times d)]$  using one subtractor and the imaginary part  $[(a \times d) + (b \times c)]$  using one adder, for data widths up to 18 bits. Two complex multiplications are possible for data widths up to 9 bits using four adder/subtractor/accumulator blocks. Figure 2–38 shows an 18-bit two-multipliers adder.

**Figure 2–38. Two-Multipliers Adder Mode Implementing Complex Multiply**



### Four-Multipliers Adder Mode

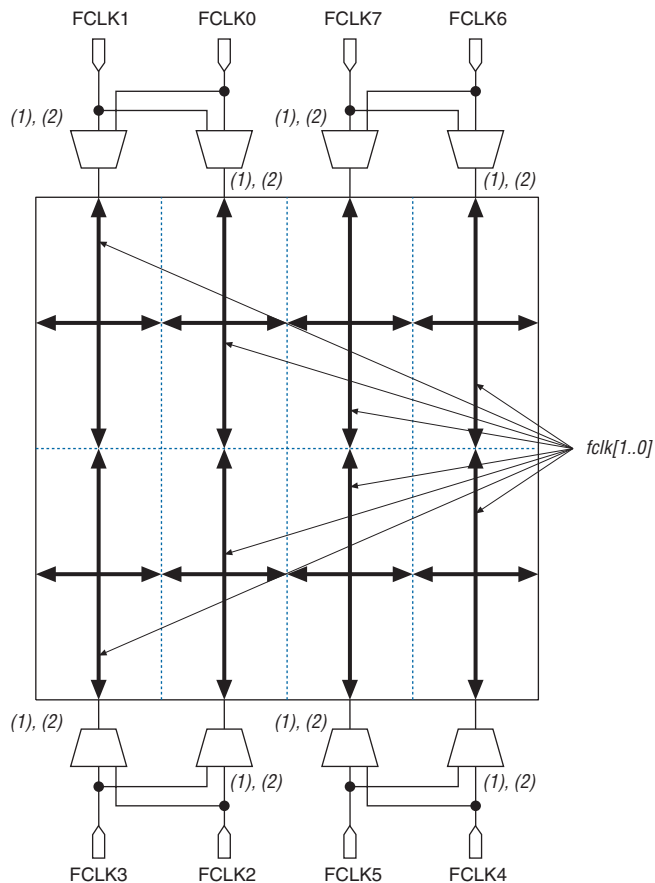
In the four-multipliers adder mode, the DSP block adds the results of two first-stage adder/subtractor blocks. One sum of four  $18 \times 18$ -bit multipliers or two different sums of two sets of four  $9 \times 9$ -bit multipliers can be implemented in a single DSP block. The product width for each multiplier must be the same size. The four-multipliers adder mode is useful for FIR filter applications. Figure 2–39 shows the four multipliers adder mode.

There are 16 dedicated clock pins (CLK [15 . . 0]) to drive either the global or regional clock networks. Four clock pins drive each side of the device, as shown in [Figure 2–42](#). Enhanced and fast PLL outputs can also drive the global and regional clock networks.

### *Global Clock Network*

These clocks drive throughout the entire device, feeding all device quadrants. The global clock networks can be used as clock sources for all resources within the device—IOEs, LEs, DSP blocks, and all memory blocks. These resources can also be used for control signals, such as clock enables and synchronous or asynchronous clears fed from the external pin. The global clock networks can also be driven by internal logic for internally generated global clocks and asynchronous clears, clock enables, or other control signals with large fanout. [Figure 2–42](#) shows the 16 dedicated CLK pins driving global clock networks.

**Figure 2–45. EP1S30 Device Fast Regional Clock Pin Connections to Fast Regional Clocks**



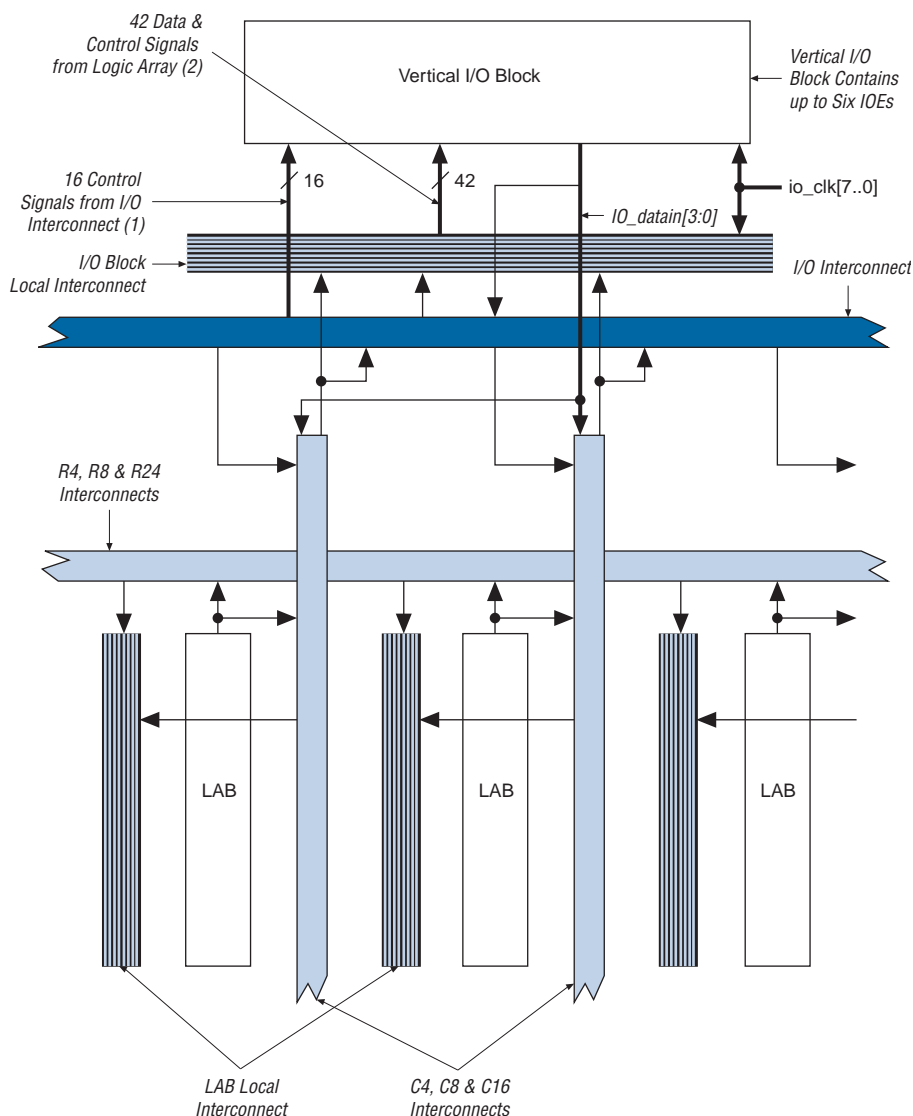
**Notes to Figure 2–45:**

- (1) This is a set of two multiplexers.
- (2) In addition to the FCLK pin inputs, there is also an input from the I/O interconnect.

### Combined Resources

Within each region, there are 22 distinct dedicated clocking resources consisting of 16 global clock lines, four regional clock lines, and two fast regional clock lines. Multiplexers are used with these clocks to form eight bit busses to drive LAB row clocks, column IOE clocks, or row IOE clocks. Another multiplexer is used at the LAB level to select two of the eight row clocks to feed the LE registers within the LAB. See Figure 2–46.

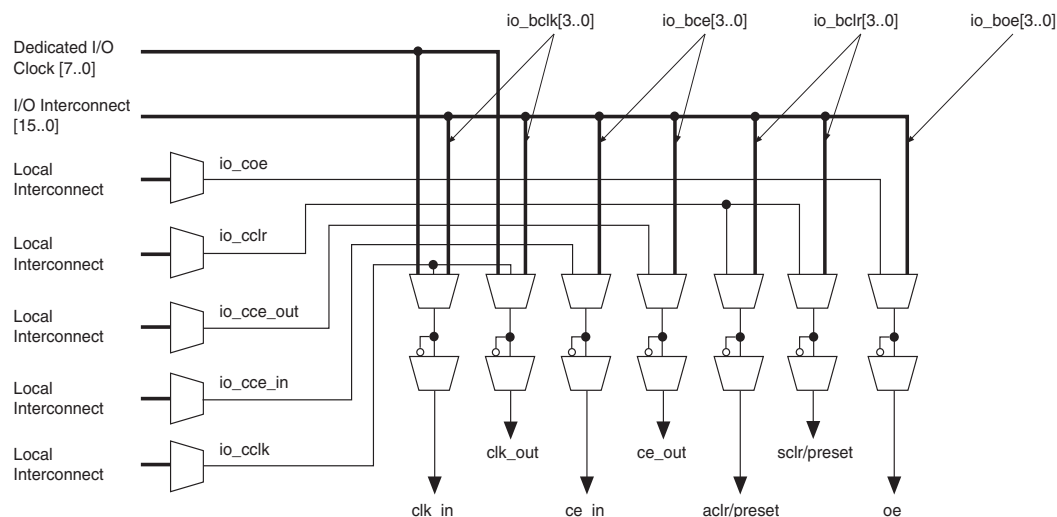


**Figure 2–61. Column I/O Block Connection to the Interconnect****Notes to Figure 2–61:**

- (1) The 16 control signals are composed of four output enables `io_boe[3..0]`, four clock enables `io_bce[3..0]`, four clocks `io_bclk[3..0]`, and four clear signals `io_bclr[3..0]`.
- (2) The 42 data and control signals consist of 12 data out lines; six lines each for DDR applications `io_dataouta[5..0]` and `io_dataoutb[5..0]`, six output enables `io_coe[5..0]`, six input clock enables `io_cce_in[5..0]`, six output clock enables `io_cce_out[5..0]`, six clocks `io_cclk[5..0]`, and six clear signals `io_cclr[5..0]`.

Each IOE contains its own control signal selection for the following control signals: oe, ce\_in, ce\_out, aclr/preset, sclr/preset, clk\_in, and clk\_out. Figure 2-63 illustrates the control signal selection.

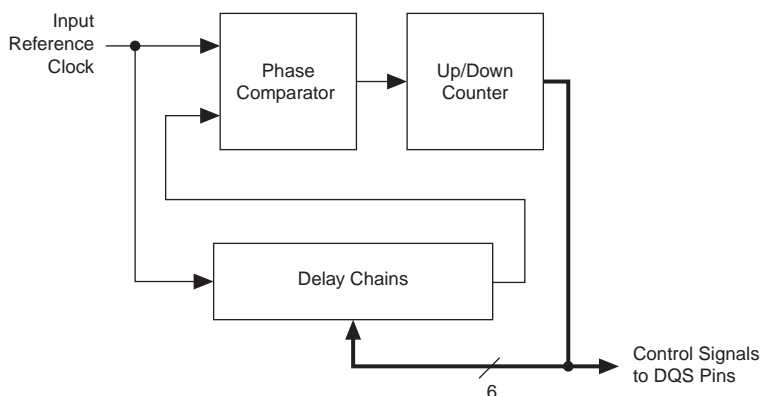
**Figure 2-63. Control Signal Selection per IOE**



In normal bidirectional operation, the input register can be used for input data requiring fast setup times. The input register can have its own clock input and clock enable separate from the OE and output registers. The output register can be used for data requiring fast clock-to-output performance. The OE register can be used for fast clock-to-output enable timing. The OE and output register share the same clock source and the same clock enable source from local interconnect in the associated LAB, dedicated I/O clocks, and the column and row interconnects. Figure 2-64 shows the IOE in bidirectional configuration.

shift by the same degree amount. For example, all 10 DQS pins on the top of the device can be shifted by  $90^\circ$  and all 10 DQS pins on the bottom of the device can be shifted by  $72^\circ$ . The reference circuits require a maximum of 256 system reference clock cycles to set the correct phase on the DQS delay elements. Figure 2–69 illustrates the phase-shift reference circuit control of each DQS delay shift on the top of the device. This same circuit is duplicated on the bottom of the device.

**Figure 2–69. Simplified Diagram of the DQS Phase-Shift Circuitry**



See the *External Memory Interfaces* chapter in the *Stratix Device Handbook, Volume 2* for more information on external memory interfaces.

## Programmable Drive Strength

The output buffer for each Stratix device I/O pin has a programmable drive strength control for certain I/O standards. The LVTTTL and LVCMOS standard has several levels of drive strength that the user can control. SSTL-3 Class I and II, SSTL-2 Class I and II, HSTL Class I and II, and 3.3-V GTL+ support a minimum setting, the lowest drive strength that guarantees the  $I_{OH}/I_{OL}$  of the standard. Using minimum settings provides signal slew rate control to reduce system noise and signal overshoot.

### IEEE Std. 1149.1 (JTAG) Boundary-Scan Support

All Stratix® devices provide JTAG BST circuitry that complies with the IEEE Std. 1149.1a-1990 specification. JTAG boundary-scan testing can be performed either before or after, but not during configuration. Stratix devices can also use the JTAG port for configuration together with either the Quartus® II software or hardware using either Jam Files (.jam) or Jam Byte-Code Files (.jbc).

Stratix devices support IOE I/O standard setting reconfiguration through the JTAG BST chain. The JTAG chain can update the I/O standard for all input and output pins any time before or during user mode through the CONFIG\_IO instruction. You can use this ability for JTAG testing before configuration when some of the Stratix pins drive or receive from other devices on the board using voltage-referenced standards. Since the Stratix device may not be configured before JTAG testing, the I/O pins may not be configured for appropriate electrical standards for chip-to-chip communication. Programming those I/O standards via JTAG allows you to fully test the I/O connection to other devices.

The enhanced PLL reconfiguration bits are part of the JTAG chain before configuration and after power-up. After device configuration, the PLL reconfiguration bits are not part of the JTAG chain.

The JTAG pins support 1.5-V/1.8-V or 2.5-V/3.3-V I/O standards. The TDO pin voltage is determined by the V<sub>CCIO</sub> of the bank where it resides. The VCCSEL pin selects whether the JTAG inputs are 1.5-V, 1.8-V, 2.5-V, or 3.3-V compatible.

Stratix devices also use the JTAG port to monitor the logic operation of the device with the SignalTap® II embedded logic analyzer. Stratix devices support the JTAG instructions shown in [Table 3-1](#).

The Quartus II software has an Auto Usercode feature where you can choose to use the checksum value of a programming file as the JTAG user code. If selected, the checksum is automatically loaded to the USERCODE register. In the Settings dialog box in the Assignments menu, click **Device & Pin Options**, then **General**, and then turn on the **Auto Usercode** option.

**Table 4–20. SSTL-2 Class I Specifications**

Symbol	Parameter	Conditions	Minimum	Typical	Maximum	Unit
$V_{CCIO}$	Output supply voltage		2.375	2.5	2.625	V
$V_{TT}$	Termination voltage		$V_{REF} - 0.04$	$V_{REF}$	$V_{REF} + 0.04$	V
$V_{REF}$	Reference voltage		1.15	1.25	1.35	V
$V_{IH(DC)}$	High-level DC input voltage		$V_{REF} + 0.18$		3.0	V
$V_{IL(DC)}$	Low-level DC input voltage		–0.3		$V_{REF} - 0.18$	V
$V_{IH(AC)}$	High-level AC input voltage		$V_{REF} + 0.35$			V
$V_{IL(AC)}$	Low-level AC input voltage				$V_{REF} - 0.35$	V
$V_{OH}$	High-level output voltage	$I_{OH} = -8.1 \text{ mA}$ (3)	$V_{TT} + 0.57$			V
$V_{OL}$	Low-level output voltage	$I_{OL} = 8.1 \text{ mA}$ (3)			$V_{TT} - 0.57$	V

**Table 4–21. SSTL-2 Class II Specifications**

Symbol	Parameter	Conditions	Minimum	Typical	Maximum	Unit
$V_{CCIO}$	Output supply voltage		2.375	2.5	2.625	V
$V_{TT}$	Termination voltage		$V_{REF} - 0.04$	$V_{REF}$	$V_{REF} + 0.04$	V
$V_{REF}$	Reference voltage		1.15	1.25	1.35	V
$V_{IH(DC)}$	High-level DC input voltage		$V_{REF} + 0.18$		$V_{CCIO} + 0.3$	V
$V_{IL(DC)}$	Low-level DC input voltage		–0.3		$V_{REF} - 0.18$	V
$V_{IH(AC)}$	High-level AC input voltage		$V_{REF} + 0.35$			V
$V_{IL(AC)}$	Low-level AC input voltage				$V_{REF} - 0.35$	V
$V_{OH}$	High-level output voltage	$I_{OH} = -16.4 \text{ mA}$ (3)	$V_{TT} + 0.76$			V
$V_{OL}$	Low-level output voltage	$I_{OL} = 16.4 \text{ mA}$ (3)			$V_{TT} - 0.76$	V

**Table 4–22. SSTL-3 Class I Specifications (Part 1 of 2)**

Symbol	Parameter	Conditions	Minimum	Typical	Maximum	Unit
$V_{CCIO}$	Output supply voltage		3.0	3.3	3.6	V
$V_{TT}$	Termination voltage		$V_{REF} - 0.05$	$V_{REF}$	$V_{REF} + 0.05$	V
$V_{REF}$	Reference voltage		1.3	1.5	1.7	V
$V_{IH(DC)}$	High-level DC input voltage		$V_{REF} + 0.2$		$V_{CCIO} + 0.3$	V
$V_{IL(DC)}$	Low-level DC input voltage		–0.3		$V_{REF} - 0.2$	V
$V_{IH(AC)}$	High-level AC input voltage		$V_{REF} + 0.4$			V

**Table 4–39. DSP Block Internal Timing Microparameter Descriptions**

Symbol	Parameter
$t_{SU}$	Input, pipeline, and output register setup time before clock
$t_H$	Input, pipeline, and output register hold time after clock
$t_{CO}$	Input, pipeline, and output register clock-to-output delay
$t_{INREG2PIPE9}$	Input Register to DSP Block pipeline register in $9 \times 9$ -bit mode
$t_{INREG2PIPE18}$	Input Register to DSP Block pipeline register in $18 \times 18$ -bit mode
$t_{PIPE2OUTREG2ADD}$	DSP Block Pipeline Register to output register delay in Two-Multipliers Adder mode
$t_{PIPE2OUTREG4ADD}$	DSP Block Pipeline Register to output register delay in Four-Multipliers Adder mode
$t_{PD9}$	Combinatorial input to output delay for $9 \times 9$
$t_{PD18}$	Combinatorial input to output delay for $18 \times 18$
$t_{PD36}$	Combinatorial input to output delay for $36 \times 36$
$t_{CLR}$	Minimum clear pulse width
$t_{CLKHL}$	Register minimum clock high or low time. This is a limit on the min time for the clock on the registers in these blocks. The actual performance is dependent upon the internal point-to-point delays in the blocks and may give slower performance as shown in <a href="#">Table 4–36 on page 4–20</a> and as reported by the timing analyzer in the Quartus II software.

Tables 4–73 through 4–78 show the external timing parameters on column and row pins for EP1S30 devices.

**Table 4–73. EP1S30 External I/O Timing on Column Pins Using Fast Regional Clock Networks**

Parameter	-5 Speed Grade		-6 Speed Grade		-7 Speed Grade		-8 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	Min	Max	
$t_{\text{INSU}}$	2.502		2.680		3.062		3.591		ns
$t_{\text{INH}}$	0.000		0.000		0.000		0.000		ns
$t_{\text{OUTCO}}$	2.473	4.965	2.473	5.329	2.473	5.784	2.473	6.392	ns
$t_{\text{XZ}}$	2.413	4.839	2.413	5.197	2.413	5.660	2.413	6.277	ns
$t_{\text{ZX}}$	2.413	4.839	2.413	5.197	2.413	5.660	2.413	6.277	ns

**Table 4–74. EP1S30 External I/O Timing on Column Pins Using Regional Clock Networks**

Parameter	-5 Speed Grade		-6 Speed Grade		-7 Speed Grade		-8 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	Min	Max	
$t_{\text{INSU}}$	2.286		2.426		2.769		3.249		ns
$t_{\text{INH}}$	0.000		0.000		0.000		0.000		ns
$t_{\text{OUTCO}}$	2.641	5.225	2.641	5.629	2.641	6.130	2.641	6.796	ns
$t_{\text{XZ}}$	2.581	5.099	2.581	5.497	2.581	6.006	2.581	6.681	ns
$t_{\text{ZX}}$	2.581	5.099	2.581	5.497	2.581	6.006	2.581	6.681	ns
$t_{\text{INSUPLL}}$	1.200		1.185		1.344		1.662		ns
$t_{\text{INHPLL}}$	0.000		0.000		0.000		0.000		ns
$t_{\text{OUTCOPLL}}$	1.108	2.367	1.108	2.534	1.108	2.569	1.108	2.517	ns
$t_{\text{XZPLL}}$	1.048	2.241	1.048	2.402	1.048	2.445	1.048	2.402	ns
$t_{\text{ZXPLL}}$	1.048	2.241	1.048	2.402	1.048	2.445	1.048	2.402	ns

**Table 4–75. EP1S30 External I/O Timing on Column Pins Using Global Clock Networks (Part 1 of 2)**

Parameter	-5 Speed Grade		-6 Speed Grade		-7 Speed Grade		-8 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	Min	Max	
$t_{\text{INSU}}$	1.935		2.029		2.310		2.709		ns
$t_{\text{INH}}$	0.000		0.000		0.000		0.000		ns
$t_{\text{OUTCO}}$	2.814	5.532	2.814	5.980	2.814	6.536	2.814	7.274	ns

**Table 4–87. EP1S60 External I/O Timing on Column Pins Using Global Clock Networks** *Note (1)*

Parameter	-5 Speed Grade		-6 Speed Grade		-7 Speed Grade		-8 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	Min	Max	
$t_{\text{INSU}}$	2.000		2.152		2.441		NA		ns
$t_{\text{INH}}$	0.000		0.000		0.000		NA		ns
$t_{\text{OUTCO}}$	3.051	5.900	3.051	6.340	3.051	6.977	NA	NA	ns
$t_{\text{XZ}}$	2.991	5.774	2.991	6.208	2.991	6.853	NA	NA	ns
$t_{\text{ZX}}$	2.991	5.774	2.991	6.208	2.991	6.853	NA	NA	ns
$t_{\text{INSUPLL}}$	1.315		1.362		1.543		NA		ns
$t_{\text{INHPLL}}$	0.000		0.000		0.000		NA		ns
$t_{\text{OUTCOPLL}}$	1.029	2.196	1.029	2.303	1.029	2.323	NA	NA	ns
$t_{\text{XZPLL}}$	0.969	2.070	0.969	2.171	0.969	2.199	NA	NA	ns
$t_{\text{ZXPLL}}$	0.969	2.070	0.969	2.171	0.969	2.199	NA	NA	ns

**Table 4–88. EP1S60 External I/O Timing on Row Pins Using Fast Regional Clock Networks** *Note (1)*

Parameter	-5 Speed Grade		-6 Speed Grade		-7 Speed Grade		-8 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	Min	Max	
$t_{\text{INSU}}$	3.144		3.393		3.867		NA		ns
$t_{\text{INH}}$	0.000		0.000		0.000		NA		ns
$t_{\text{OUTCO}}$	2.643	5.275	2.643	5.654	2.643	6.140	NA	NA	ns
$t_{\text{XZ}}$	2.670	5.329	2.670	5.710	2.670	6.208	NA	NA	ns
$t_{\text{ZX}}$	2.670	5.329	2.670	5.710	2.670	6.208	NA	NA	ns



**Table 4–104. Stratix I/O Standard Row Pin Input Delay Adders**

Parameter	-5 Speed Grade		-6 Speed Grade		-7 Speed Grade		-8 Speed Grade		Unit
	Min	Max	Min	Max	Min	Max	Min	Max	
LVC MOS		0		0		0		0	ps
3.3-V LVTTTL		0		0		0		0	ps
2.5-V LVTTTL		21		22		25		29	ps
1.8-V LVTTTL		181		190		218		257	ps
1.5-V LVTTTL		300		315		362		426	ps
GTL+		–152		–160		–184		–216	ps
CTT		–168		–177		–203		–239	ps
SSTL-3 Class I		–193		–203		–234		–275	ps
SSTL-3 Class II		–193		–203		–234		–275	ps
SSTL-2 Class I		–262		–276		–317		–373	ps
SSTL-2 Class II		–262		–276		–317		–373	ps
SSTL-18 Class I		–105		–111		–127		–150	ps
SSTL-18 Class II		0		0		0		0	ps
1.5-V HSTL Class I		–151		–159		–183		–215	ps
1.8-V HSTL Class I		–126		–133		–153		–179	ps
LVDS		–149		–157		–180		–212	ps
LVPECL		–149		–157		–180		–212	ps
3.3-V PCML		–65		–69		–79		–93	ps
HyperTransport		77		–81		–93		–110	ps

**Table 4–107. Stratix I/O Standard Output Delay Adders for Slow Slew Rate on Column Pins (Part 2 of 2)**

Parameter		-5 Speed Grade		-6 Speed Grade		-7 Speed Grade		-8 Speed Grade		Unit
		Min	Max	Min	Max	Min	Max	Min	Max	
3.3-V LVTTTL	4 mA		1,822		1,913		1,913		1,913	ps
	8 mA		1,586		1,665		1,665		1,665	ps
	12 mA		686		720		720		720	ps
	16 mA		630		662		662		662	ps
	24 mA		0		0		0		0	ps
2.5-V LVTTTL	2 mA		2,925		3,071		3,071		3,071	ps
	8 mA		1,496		1,571		1,571		1,571	ps
	12 mA		937		984		984		984	ps
	16 mA		1,003		1,053		1,053		1,053	ps
1.8-V LVTTTL	2 mA		7,101		7,456		7,456		7,456	ps
	8 mA		3,620		3,801		3,801		3,801	ps
	12 mA		3,109		3,265		3,265		3,265	ps
1.5-V LVTTTL	2 mA		10,941		11,488		11,488		11,488	ps
	4 mA		7,431		7,803		7,803		7,803	ps
	8 mA		5,990		6,290		6,290		6,290	ps
GTL			–959		–1,007		–1,007		–1,007	ps
GTL+			–438		–460		–460		–460	ps
3.3-V PCI			660		693		693		693	ps
3.3-V PCI-X 1.0			660		693		693		693	ps
Compact PCI			660		693		693		693	ps
AGP 1×			660		693		693		693	ps
AGP 2×			288		303		303		303	ps
CTT			631		663		663		663	ps
SSTL-3 Class I			301		316		316		316	ps
SSTL-3 Class II			–359		–377		–377		–377	ps
SSTL-2 Class I			523		549		549		549	ps
SSTL-2 Class II			–49		–51		–51		–51	ps
SSTL-18 Class I			2,315		2,431		2,431		2,431	ps
SSTL-18 Class II			723		759		759		759	ps
1.5-V HSTL Class I			1,687		1,771		1,771		1,771	ps
1.5-V HSTL Class II			1,095		1,150		1,150		1,150	ps
1.8-V HSTL Class I			599		629		678		744	ps
1.8-V HSTL Class II			87		102		102		102	ps

**Table 4–117. Stratix Maximum Input Clock Rate for CLK[7..4] & CLK[15..12] Pins in Wire-Bond Packages (Part 2 of 2)**

I/O Standard	-6 Speed Grade	-7 Speed Grade	-8 Speed Grade	Unit
GTL+	250	200	200	MHz
SSTL-3 Class I	300	250	250	MHz
SSTL-3 Class II	300	250	250	MHz
SSTL-2 Class I	300	250	250	MHz
SSTL-2 Class II	300	250	250	MHz
SSTL-18 Class I	300	250	250	MHz
SSTL-18 Class II	300	250	250	MHz
1.5-V HSTL Class I	300	180	180	MHz
1.5-V HSTL Class II	300	180	180	MHz
1.8-V HSTL Class I	300	180	180	MHz
1.8-V HSTL Class II	300	180	180	MHz
3.3-V PCI	422	390	390	MHz
3.3-V PCI-X 1.0	422	390	390	MHz
Compact PCI	422	390	390	MHz
AGP 1×	422	390	390	MHz
AGP 2×	422	390	390	MHz
CTT	250	180	180	MHz
Differential 1.5-V HSTL C1	300	180	180	MHz
LVPECL (1)	422	400	400	MHz
PCML (1)	215	200	200	MHz
LVDS (1)	422	400	400	MHz
HyperTransport technology (1)	422	400	400	MHz

**Table 4–118. Stratix Maximum Input Clock Rate for CLK[0, 2, 9, 11] Pins & FPLL[10..7]CLK Pins in Wire-Bond Packages (Part 1 of 2)**

I/O Standard	-6 Speed Grade	-7 Speed Grade	-8 Speed Grade	Unit
LVTTL	422	390	390	MHz
2.5 V	422	390	390	MHz
1.8 V	422	390	390	MHz
1.5 V	422	390	390	MHz



Differential HSTL Specifications 4-15

DSP

Block Diagram

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for 9 x 9-Bit 2-56

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Multiplier

2-60

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## E

EP1S10 Devices

Column Pin

Fast Regional Clock External I/O Timing  
Parameters 4-36

Global Clock External I/O Timing  
Parameters 4-37

Regional Clock External I/O Timing  
Parameters 4-36

Row Pin

Fast Regional Clock External I/O Timing  
Parameters 4-37

Global Clock External I/O Timing  
Parameters 4-38

Regional Clock External I/O Timing  
Parameters 4-38

EP1S20 Devices

Column Pin

Fast Regional Clock External I/O Timing  
Parameters 4-39

Global Clock External I/O Timing  
Parameters 4-40

Regional Clock External I/O Timing

Parameters 4-39

Row Pin

Fast Regional Clock External I/O Timing  
Parameters 4-40

Global Clock External I/O Timing  
Parameters 4-41

Regional Clock External I/O Timing  
Parameters 4-41

EP1S25 Devices

Column Pin

Fast Regional Clock External I/O Timing  
Parameters 4-42

Global Clock External I/O Timing  
Parameters 4-43

Regional Clock External I/O Timing  
Parameters 4-42

Row Pin

Fast Regional Clock External I/O Timing  
Parameters 4-43

Global Clock External I/O Timing  
Parameters 4-44

Regional Clock External I/O Timing  
Parameters 4-44

EP1S30 Devices

Column Pin

Fast Regional Clock External I/O Timing  
Parameters 4-45

Global Clock External I/O Timing  
Parameters 4-45

Regional Clock External I/O Timing  
Parameters 4-45

Row Pin

Fast Regional Clock External I/O Timing  
Parameters 4-46

Global Clock External I/O Timing  
Parameters 4-47

Regional Clock External I/O Timing  
Parameters 4-47

EP1S40 Devices

Column Pin

Fast Regional Clock External I/O Timing  
Parameters 4-48

Global Clock External I/O Timing  
Parameters 4-49

Regional Clock External I/O Timing  
Parameters 4-48

Row Pin